

500kHz, Rail-to-Rail I/O CMOS Operational Amplifier

1 FEATURES

- **GAIN BANDWIDTH: 500kHz**
- **RAIL-TO-RAIL INPUT AND OUTPUT**
±0.8mV Typical Vos
- **INPUT VOLTAGE RANGE: -0.1V to +5.6V**
with Vs = 5.5V
- **SUPPLY RANGE: +2.5V to +5.5V**
- **SHUTDOWN: RS221S/RS222S**
- **SPECIFIED UP TO +125°C**
- **Micro SIZE PACKAGES: SOT23-5, SOT23-6**

2 APPLICATIONS

- **SENSORS**
- **PHOTODIODE AMPLIFICATION**
- **ACTIVE FILTERS**
- **TEST EQUIPMENT**
- **DRIVING A/D CONVERTERS**

3 DESCRIPTIONS

The RS221, RS222, RS224, RS221S, RS222S families of products offer low voltage operation and rail-to-rail input and output, as well as excellent speed/power consumption ratio, providing an excellent bandwidth (500kHz) and slew rate of 0.18V/us. The op-amps are unity gain stable and feature an ultra-low input bias current.

The devices are ideal for sensor interfaces, active filters and portable applications. The RS221S, RS222S include a shutdown mode. Under logic control, the amplifiers can be switched from normal operation to a standby current that is less than 1uA. The RS221, RS222, RS224, RS221S, RS222S families of operational amplifiers are specified at the full temperature range of -40°C to +125°C under single or dual power supplies of 2.5V to 5.5V.

Device Information ⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE(NOM)
RS221	SOT23-5	2.90mm×1.60mm
	SOP8	4.90mm×3.90mm
	MSOP8	3.00mm×3.00mm
RS221S	SOT23-6	2.90mm×1.60mm
	SOP8	4.90mm×3.90mm
RS222	SOP8	4.90mm×3.90mm
	MSOP8	3.00mm×3.00mm
	DFN3X3-8	3.00mm×3.00mm
RS222S	MSOP10	3.00mm×3.00mm
RS224	SOP14	8.65mm×3.90mm
	TSSOP14	5.00mm×4.40mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

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4 Revision History

Note: Page numbers for previous revisions may differ from page numbers in the current version.

Version	Change Date	Change Item
C.1	2022/04/21	1. Update Package Qty on Page 2@RevB.2 2. Added the TAPE AND REEL INFORMATION
C.2	2023/09/22	1.Update ELECTRICAL CHARACTERISTICS on Page 9@RevC.1 2. Added Pin Description
C.2.1	2024/03/04	Modify packaging naming

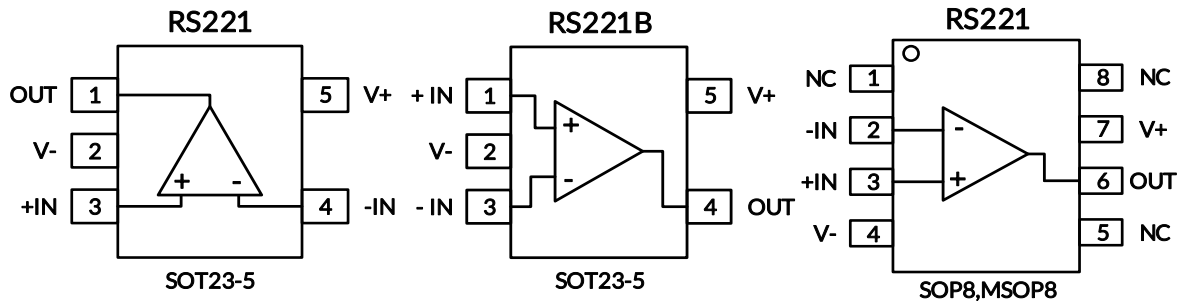
5 PACKAGE/ORDERING INFORMATION ⁽¹⁾

Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking ⁽²⁾	Package Qty
RS221XF	SOT23-5	5	1	-40°C ~125°C	221	Tape and Reel,3000
RS221BXF	SOT23-5	5	1	-40°C ~125°C	221B	Tape and Reel,3000
RS221XK	SOP8	8	1	-40°C ~125°C	RS221	Tape and Reel,4000
RS221XM	MSOP8	8	1	-40°C ~125°C	RS221	Tape and Reel,4000
RS221SXK	SOP8	8	1	-40°C ~125°C	RS221S	Tape and Reel,4000
RS221SXH	SOT23-6	6	1	-40°C ~125°C	221S	Tape and Reel,3000
RS222XK	SOP8	8	2	-40°C ~125°C	RS222	Tape and Reel,4000
RS222XM	MSOP8	8	2	-40°C ~125°C	RS222	Tape and Reel,4000
RS222XT	DFN3X3-8	8	2	-40°C ~125°C	RS222	Tape and Reel,5000
RS222SXN	MSOP10	10	2	-40°C ~125°C	RS222S	Tape and Reel,4000
RS224XP	SOP14	14	4	-40°C ~125°C	RS224	Tape and Reel,4000
RS224XQ	TSSOP14	14	4	-40°C ~125°C	RS224	Tape and Reel,4000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.

6 Pin Configuration and Functions (Top View)

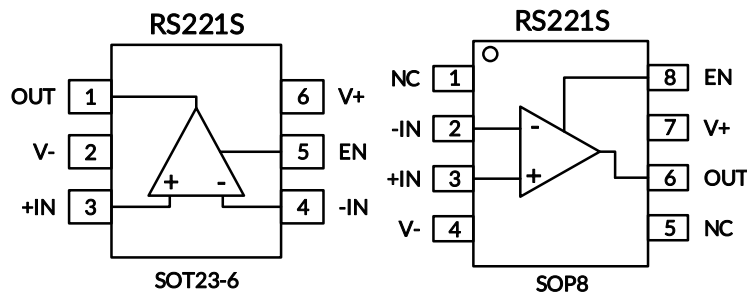


Pin Description

NAME	PIN			I/O ⁽¹⁾	DESCRIPTION
	RS221	RS221B	RS221		
	SOT23-5	SOT23-5	SOP8/MSOP8		
-IN	4	3	2	I	Negative (inverting) input
+IN	3	1	3	I	Positive (noninverting) input
NC ⁽²⁾	-	-	1,5,8	-	No internal connection (can be left floating)
OUT	1	4	6	O	Output
V-	2	2	4	-	Negative (lowest) power supply
V+	5	5	7	-	Positive (highest) power supply

(1) I = Input, O = Output.

(2) There is no internal connection. Typically, GND is the recommended connection to a heat spreading plane.



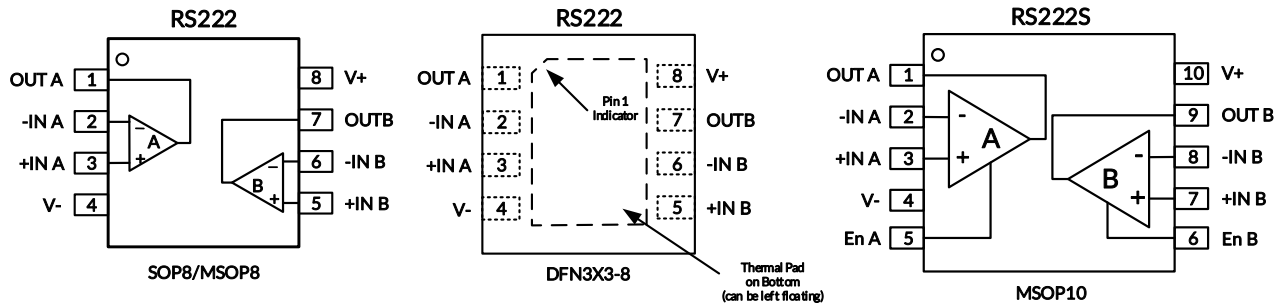
Pin Description

NAME	PIN		I/O ⁽¹⁾	DESCRIPTION
	RS221S			
	SOT23-6	SOP8		
-IN	4	2	I	Inverting input
+IN	3	3	I	Noninverting input
OUT	1	6	O	Output
EN	5	8	I	Enable pin. This pin turns the regulator on or off. Low = disabled, high = normal operation (pin must be driven)
NC ⁽²⁾	-	1,5	-	No internal connection (can be left floating)
V-	2	4	-	Negative (lowest) power supply
V+	6	7	-	Positive (highest) power supply

(1) I = Input, O = Output.

(2) There is no internal connection. Typically, GND is the recommended connection to a heat spreading plane.

Pin Configuration and Functions (Top View)

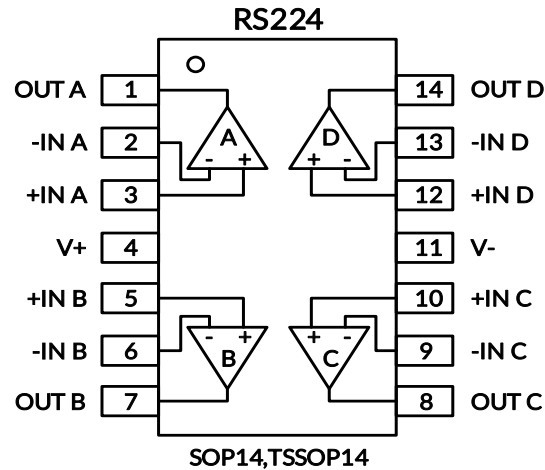


Pin Description

NAME	PIN		I/O ⁽¹⁾	DESCRIPTION
	RS222	RS222S		
	SOP8/MSOP8/ DFN3X3-8	MSOP10		
-INA	2	2	I	Inverting input, channel A
+INA	3	3	I	Noninverting input, channel A
-INB	6	8	I	Inverting input, channel B
+INB	5	7	I	Noninverting input, channel B
OUTA	1	1	O	Output, channel A
OUTB	7	9	O	Output, channel B
EnA	-	5	I	Enable pin, channel A. This pin turns the regulator on or off. Low = disabled, high = normal operation (pin must be driven)
EnB	-	6	I	Enable pin, channel B. This pin turns the regulator on or off. Low = disabled, high = normal operation (pin must be driven)
V-	4	4	-	Negative (lowest) power supply
V+	8	10	-	Positive (highest) power supply
-	Thermal Pad	-	-	Connect thermal pad to V-

(1) I = Input, O = Output.

Pin Configuration and Functions (Top View)



Pin Description

NAME	PIN	I/O ⁽¹⁾	DESCRIPTION
	SOP14/TSSOP14		
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
-INC	9	I	Inverting input, channel C
+INC	10	I	Noninverting input, channel C
-IND	13	I	Inverting input, channel D
+IND	12	I	Noninverting input, channel D
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
OUTC	8	O	Output, channel C
OUTD	14	O	Output, channel D
V-	11	-	Negative (lowest) power supply
V+	4	-	Positive (highest) power supply

(1) I = Input, O = Output.

7 SPECIFICATIONS

7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
Voltage	Supply, $V_s=(V+) - (V-)$		7	V
	Signal input pin ⁽²⁾	(V-)-0.5	(V+) +0.5	
	Signal output pin ⁽³⁾	(V-)-0.5	(V+) +0.5	
Current	Signal input pin ⁽²⁾	-10	10	mA
	Signal output pin ⁽³⁾	-50	50	mA
	Output short-circuit ⁽⁴⁾	Continuous		
θ_{JA}	Package thermal impedance ⁽⁵⁾	SOT23-5	230	°C/W
		SOP8	110	
		MSOP8	170	
		SOP14	105	
		TSSOP14	90	
		SOT23-6	230	
		DFN3X3-8	45	
MSOP10	200			
Temperature	Operating range, T_A	-40	125	°C
	Junction, T_J ⁽⁶⁾	-40	150	
	Storage, T_{stg}	-65	150	

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.

(3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.5V beyond the supply rails should be current-limited to ± 50 mA or less.

(4) Short-circuit to ground, one amplifier per package.

(5) The package thermal impedance is calculated in accordance with JESD-51.

(6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM)	± 5000
		Machine Model (MM)	± 400



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage, $V_S = (V+) - (V-)$	Single-supply	2.5		5.5	V
	Dual-supply	±1.25		±2.75	

7.4 ELECTRICAL CHARACTERISTICS

(At $T_A = +25^\circ\text{C}$, $V_S=5\text{V}$, $R_L = 200\text{k}\Omega$ connected to $V_S/2$, and $V_{OUT} = V_S/2$, $V_{CM} = V_S/2$, Full ⁽⁹⁾ = -40°C to $+125^\circ\text{C}$, unless otherwise noted.) ⁽¹⁾

PARAMETER		CONDITIONS	T_J	RS221S, RS222S, RS221, RS222, RS224			
				MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
POWER SUPPLY							
V_S	Operating Voltage Range		25°C	2.5		5.5	V
I_Q	Quiescent Current Per Amplifier		25°C		26	40	μA
PSRR	Power-Supply Rejection Ratio	$V_S=2.5\text{V}$ to 5.5V $V_{CM}=(V_-)+0.5\text{V}$	25°C	73	90		dB
			Full	67			
INPUT							
V_{OS}	Input Offset Voltage	$V_{CM} = V_S/2$	25°C	-3.5	± 0.8	3.5	mV
$V_{OS\ T_C}$	Input Offset Voltage Average Drift	$V_{CM} = V_S/2$	Full		± 2.9		$\mu\text{V}/^\circ\text{C}$
I_B	Input Bias Current ^{(4) (5)}		25°C		± 1	± 10	pA
I_{OS}	Input Offset Current ⁽⁴⁾		25°C		± 1	± 10	pA
V_{CM}	Common-Mode Voltage Range	$V_S = 5.5\text{V}$	25°C	-0.1		5.6	V
CMRR	Common-Mode Rejection Ratio	$V_S = 5.5\text{V}$ $V_{CM} = -0.1\text{V}$ to 4V	25°C	74	90		dB
			Full	70			
		$V_S = 5.5\text{V}$ $V_{CM} = -0.1\text{V}$ to 5.6V	25°C	62	75		
			Full	60			
OUTPUT							
A_{OL}	Open-Loop Voltage Gain	$R_L = 2\text{k}\Omega$, $V_O = 0.15\text{V}$ to 4.85V	25°C	88	98		dB
			Full	82			
		$R_L = 10\text{k}\Omega$, $V_O = 0.05\text{V}$ to 4.95V	25°C	92	110		
			Full	88			
	Output Swing From Rail	$R_L = 2\text{k}\Omega$	25°C		26		mV
		$R_L = 10\text{k}\Omega$			6		
I_{OUT}	Output Short-Circuit Current ^{(6) (7)}		25°C		± 27		mA
FREQUENCY RESPONSE							
SR	Slew Rate ⁽⁸⁾		25°C		0.18		V/ μs
GBP	Gain-Bandwidth Product		25°C		500		kHz
PM	Phase Margin		25°C		64		$^\circ$
t_s	Settling Time, 0.1%		25°C		14		μs
	Overload Recovery Time	$V_{IN} \cdot \text{Gain} \geq V_S$	25°C		5		μs
NOISE							
e_n	Input Voltage Noise Density	$f = 1\text{KHz}$	25°C		30		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{KHz}$	25°C		20		$\text{nV}/\sqrt{\text{Hz}}$
ENABLE/SHUTDOWN(RS221S, RS222S)							
$I_{Q(OFF)}$	Supply Current in Shutdown		25°C		<1		μA
t_{OFF}			25°C		3		μs
t_{ON}			25°C		20		μs
V_L	Shut Down		25°C	V_-		$(V_-)+0.8$	V
V_H	Amplifier Is Active		25°C	$(V_-)+2$		V_+	V

NOTE:

- (1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.
- (4) This parameter is ensured by design and/or characterization and is not tested in production.
- (5) Positive current corresponds to current flowing into the device.
- (6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $PD = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.
- (7) Short circuit test is a momentary test.
- (8) Number specified is the slower of positive and negative slew rates.
- (9) Specified by characterization only.

7.5 TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 200\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, unless otherwise noted.

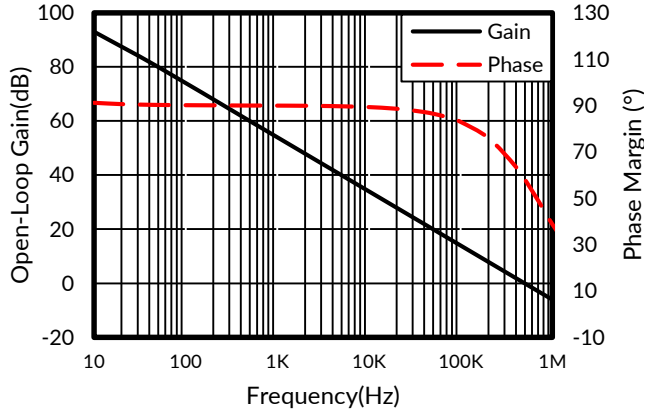


Figure 1. Open-Loop Gain and Phase vs Frequency

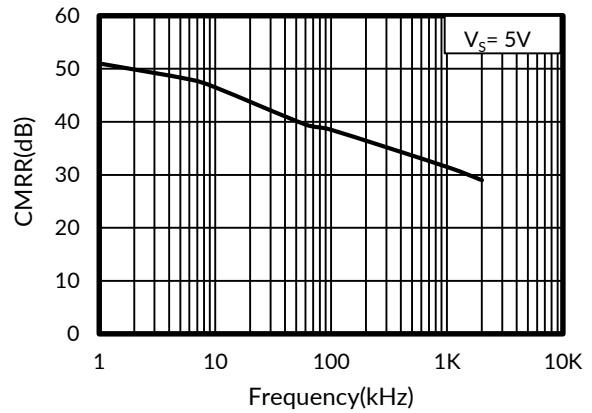


Figure 2. Common-Mode Rejection Ratio vs Frequency

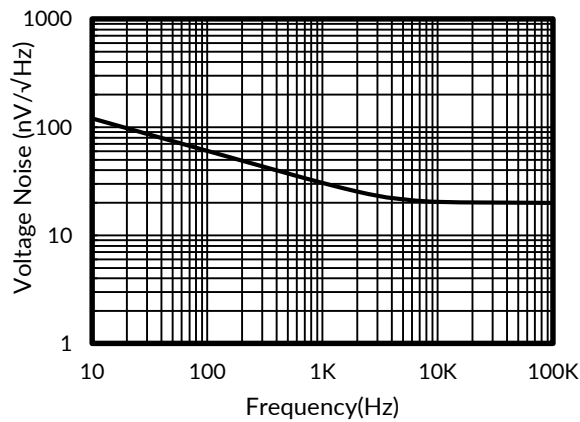


Figure 3. Input Voltage Noise Spectral Density vs Frequency

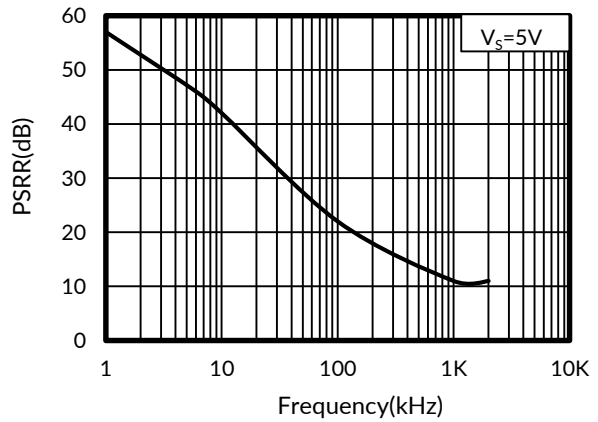


Figure 4. Power-Supply Rejection Ratio vs Frequency

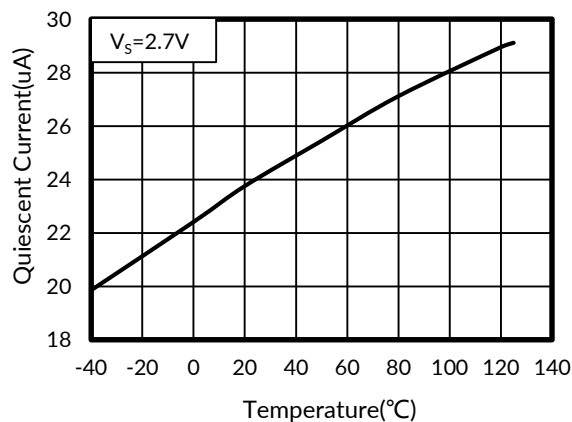


Figure 5. Quiescent Current vs Temperature

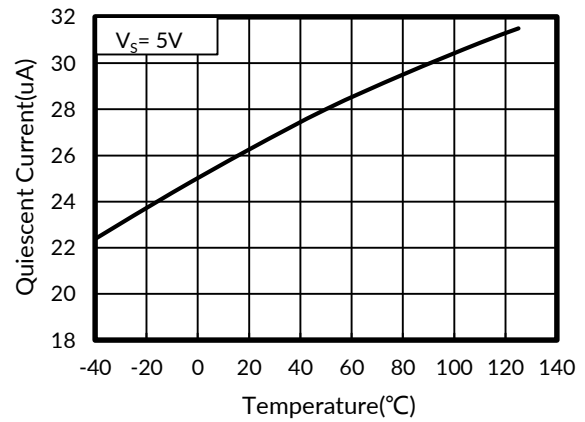


Figure 6. Quiescent Current vs Temperature

TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 200\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, unless otherwise noted.

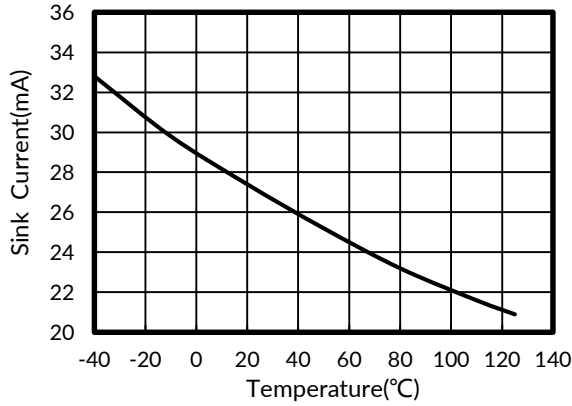


Figure 7. Sink Current vs Temperature

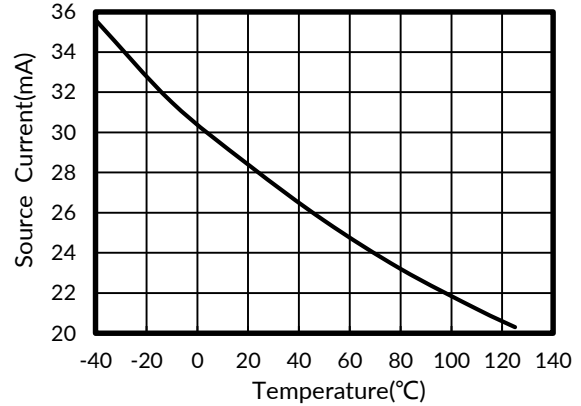


Figure 8. Source Current vs Temperature

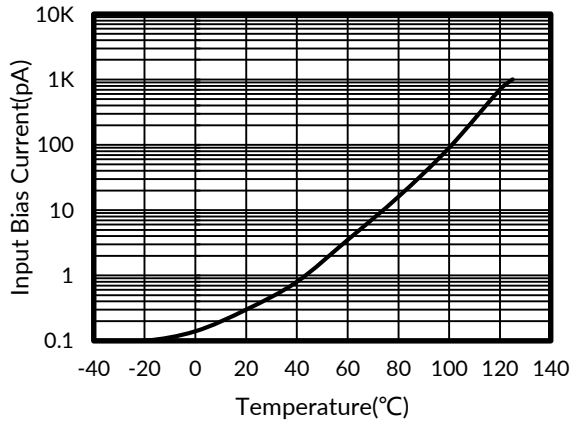


Figure 9. Input Bias Current vs Temperature

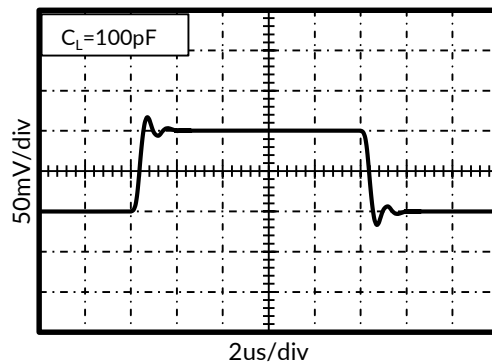


Figure 10. Small-Signal Step Response

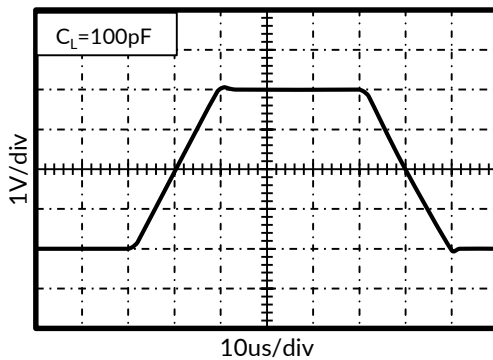


Figure 11. Large-Signal Step Response

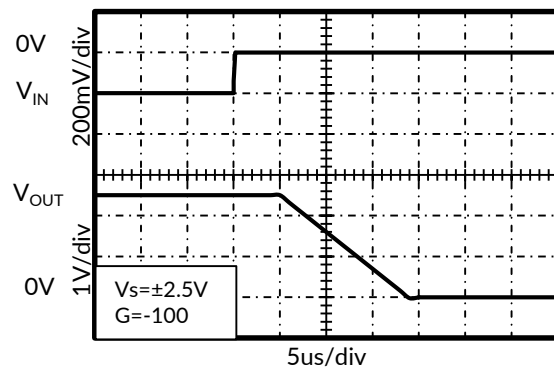


Figure 12. Positive Overtolerance Recovery

TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 200\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, unless otherwise noted.

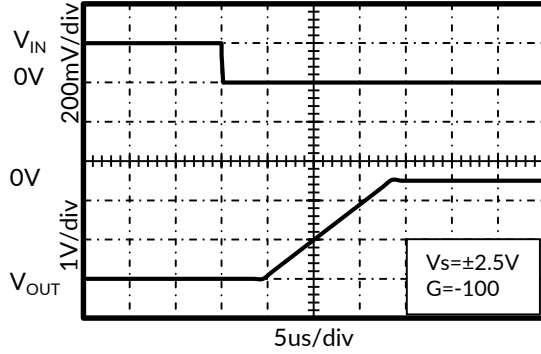


Figure 13. Negative Overvoltage Recovery

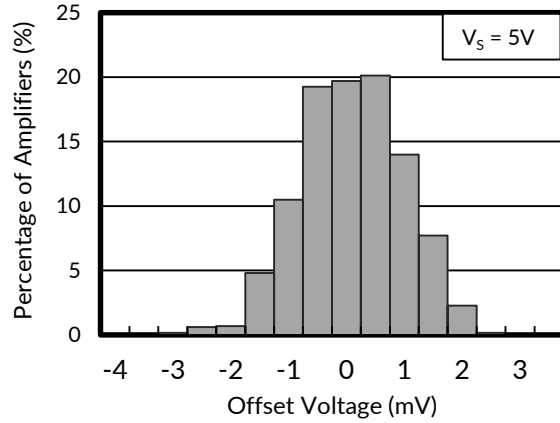


Figure 14. Offset Voltage Production Distribution

8 Application and Implementation

Information in the following applications sections is not part of the Runic component specification, and Runic does not warrant its accuracy or completeness. Runic's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 APPLICATION NOTES

The RS221, RS222, RS224, RS221S, RS222S are high precision, rail-to-rail operational amplifiers that can be run from a single-supply voltage 2.5V to 5.5V ($\pm 1.25V$ to $\pm 2.75V$). Supply voltages higher than 7V (absolute maximum) can permanently damage the amplifier. Rail-to-rail input and output swing significantly increases dynamic range, especially in low-supply applications. Good layout practice mandates use of a 0.1uF capacitor placed closely across the supply pins.

8.2 RS221S/RS222S ENABLE FUNCTION

The RS221S/RS222S includes a shutdown mode. Under logic control, the amplifiers can be switched from normal mode to a standby current of 1uA. When the Enable pin is connected to high, the amplifier is active. Connecting Enable low disables the amplifier, and places the amplifier, and place the output in a high-impedance state.

8.3 LAYOUT GUIDELINS

Attention to good layout practices is always recommended. Keep traces short. When possible, use a PCB ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1uF capacitor closely across the supply pins. These guidelines should be applied throughout the analog circuit to improve performance and provide benefits such as reducing the EMI susceptibility.

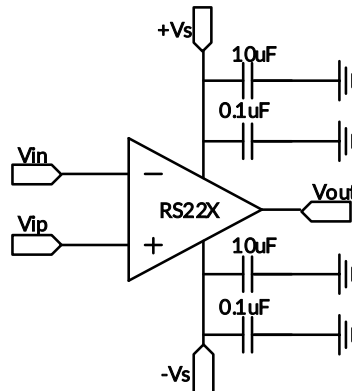


Figure 15. Amplifier with Bypass Capacitors

8.4 INSTRUMENTATION AMPLIFIER

In the three-op amp, instrumentation amplifier configuration shown in Figure 16,

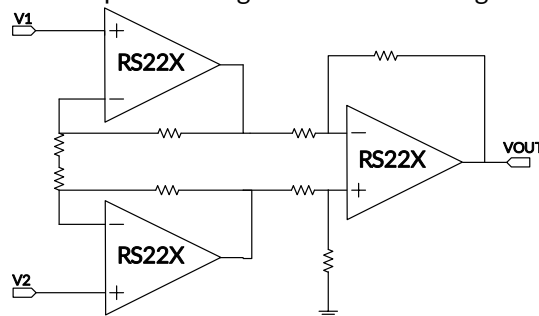
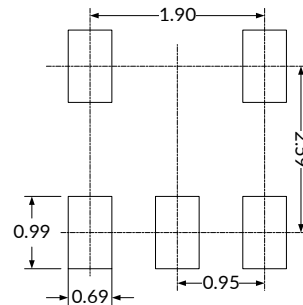
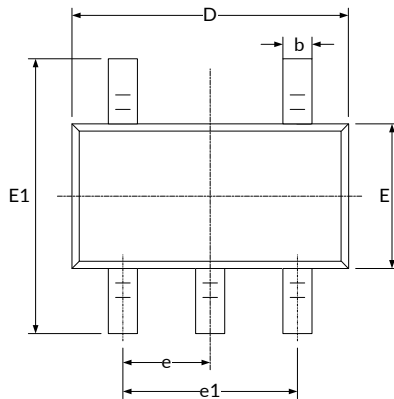
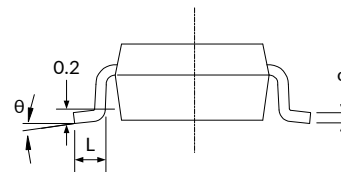
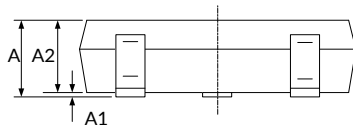


Figure 16. Amplifier instrumentation amplifier

9 PACKAGE OUTLINE DIMENSIONS SOT23-5⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)

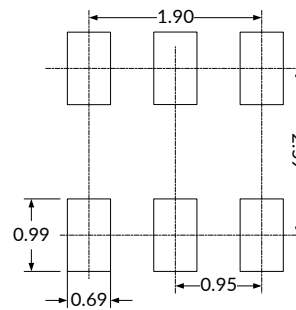
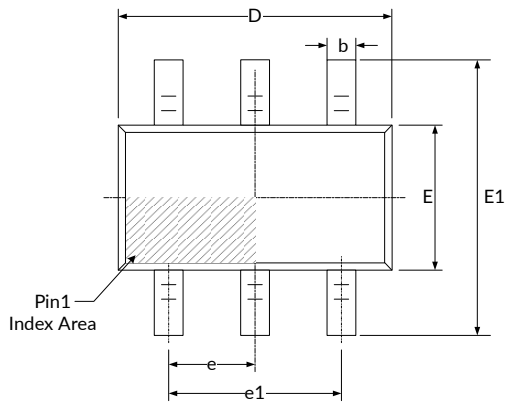


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D ⁽¹⁾	2.820	3.020	0.111	0.119
E ⁽¹⁾	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) ⁽²⁾		0.037(BSC) ⁽²⁾	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

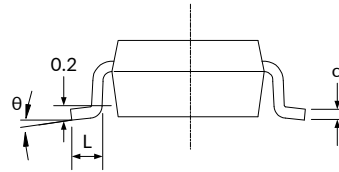
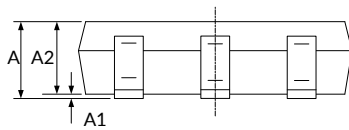
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOT23-6⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)

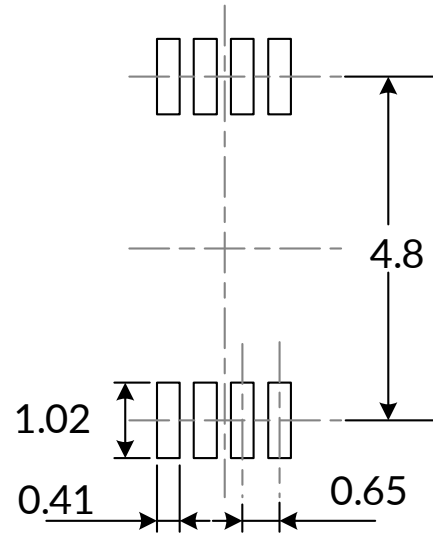
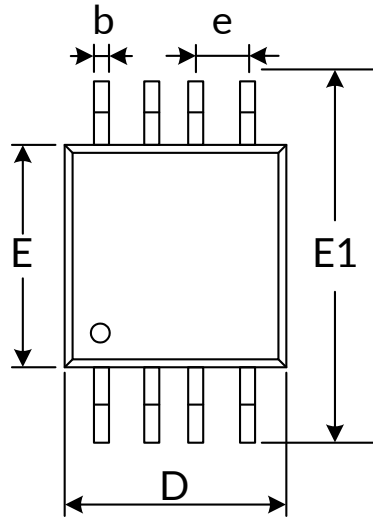


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D ⁽¹⁾	2.820	3.020	0.111	0.119
E ⁽¹⁾	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) ⁽²⁾		0.037(BSC) ⁽²⁾	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

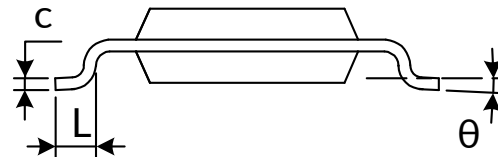
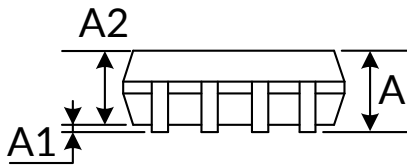
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

MSOP8⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)

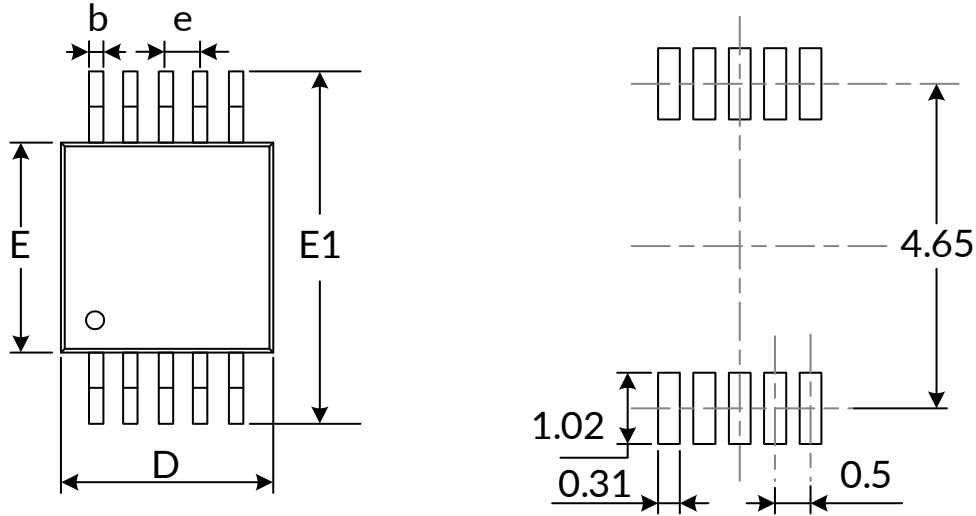


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D ⁽¹⁾	2.900	3.100	0.114	0.122
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
E ⁽¹⁾	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

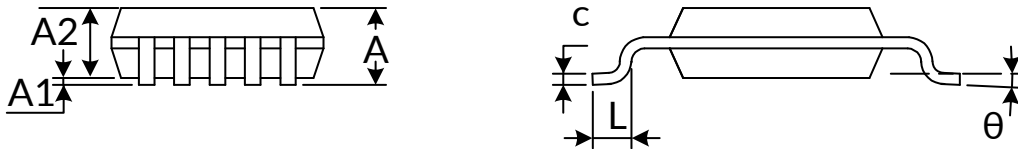
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

MSOP10⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)

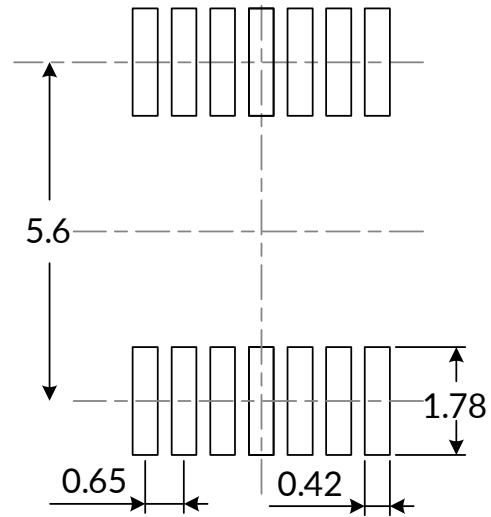
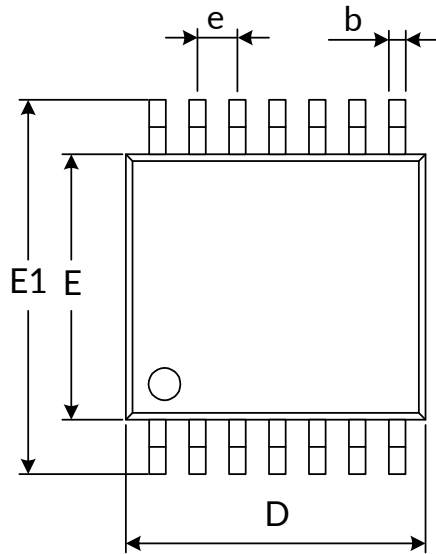


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.180	0.280	0.007	0.011
c	0.090	0.230	0.004	0.009
D ⁽¹⁾	2.900	3.100	0.114	0.122
e	0.50(BSC) ⁽²⁾		0.020(BSC) ⁽²⁾	
E ⁽¹⁾	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

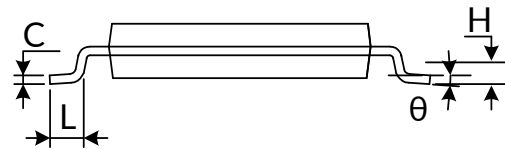
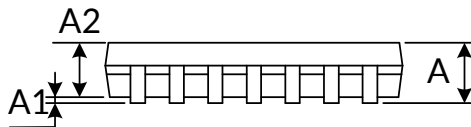
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

TSSOP14 (3)



RECOMMENDED LAND PATTERN (Unit: mm)

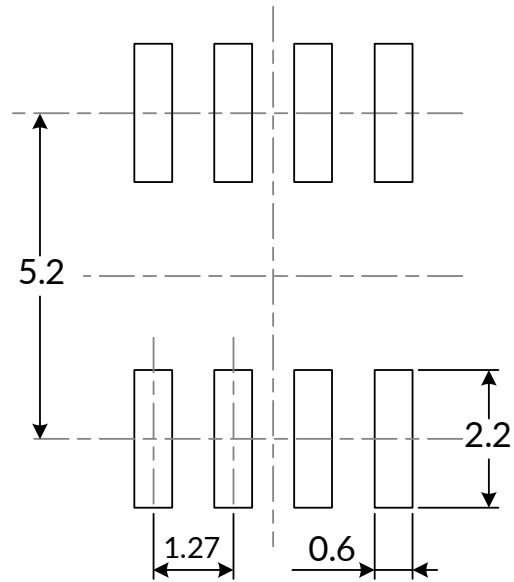
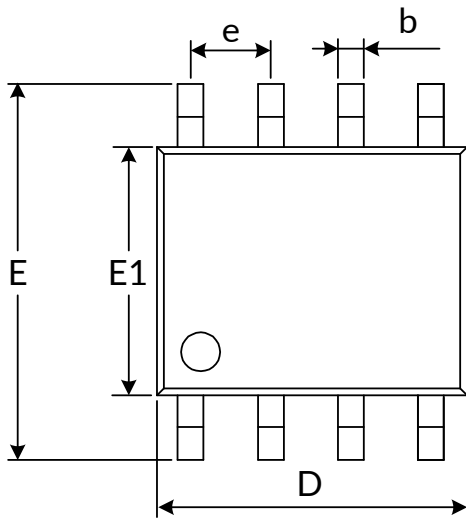


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D ⁽¹⁾	4.860	5.100	0.191	0.201
E ⁽¹⁾	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
L	0.500	0.700	0.020	0.028
H	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°

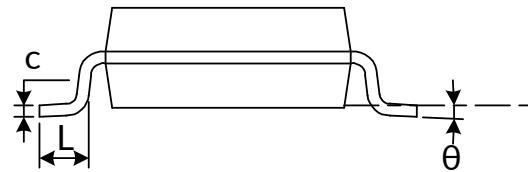
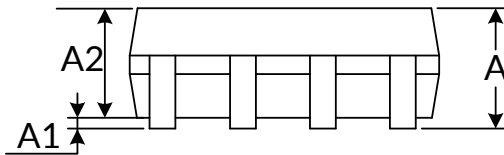
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOP8⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)

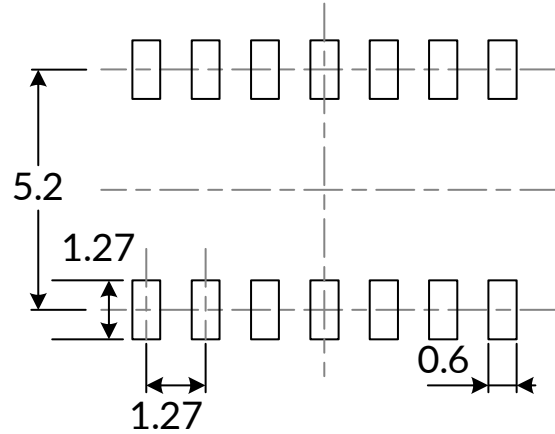
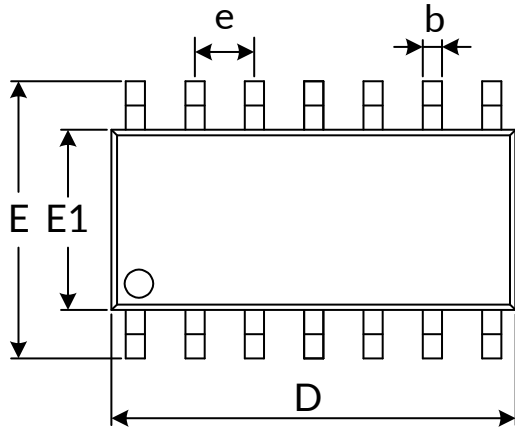


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D ⁽¹⁾	4.800	5.000	0.189	0.197
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

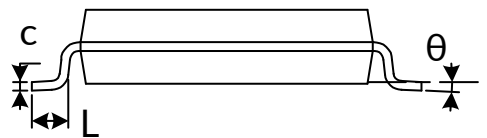
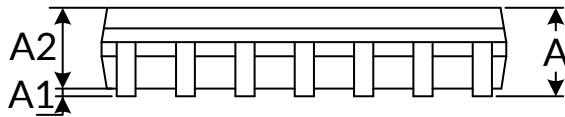
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOP14 (3)



RECOMMENDED LAND PATTERN (Unit: mm)

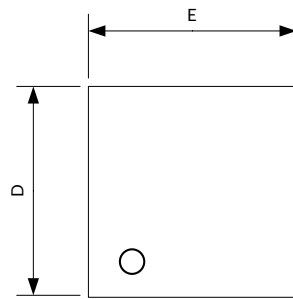


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D ⁽¹⁾	8.450	8.850	0.333	0.348
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

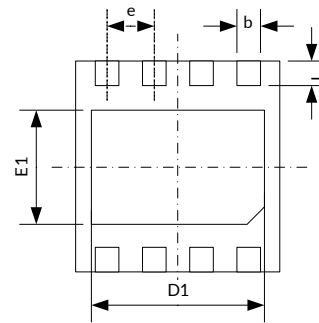
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

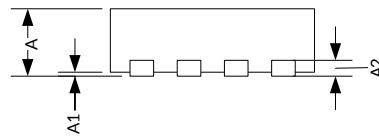
DFN3X3-8 (2)



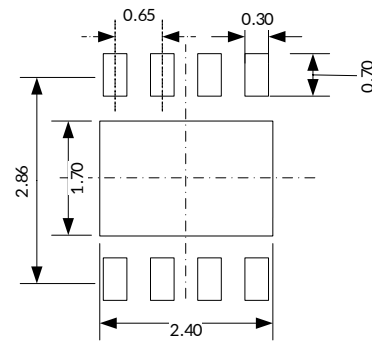
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN
(Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203		0.008	
b	0.250	0.350	0.010	0.014
D ⁽¹⁾	2.900	3.100	0.114	0.122
D1	2.350	2.450	0.093	0.096
E ⁽¹⁾	2.900	3.100	0.114	0.122
E1	1.650	1.750	0.065	0.069
e	0.650 TYP		0.026 TYP	
L	0.370	0.470	0.015	0.019

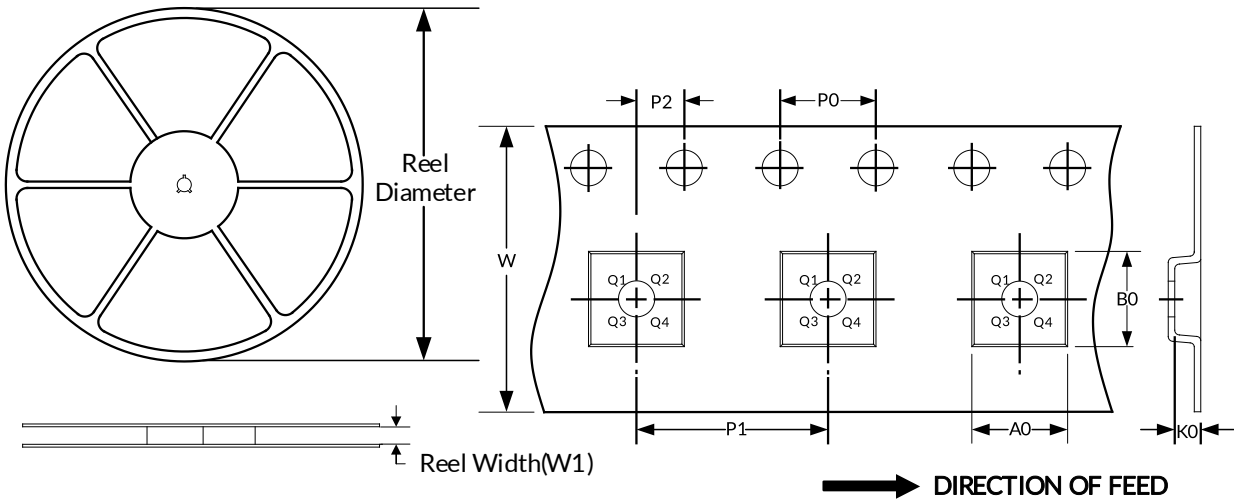
NOTE:

1. Plastic or metal protrusions of 0.075mm maximum per side are not included.
2. This drawing is subject to change without notice.

10 TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-5	7"	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
SOT23-6	7"	9.5	3.17	3.23	1.37	4.0	4.0	2.0	8.0	Q3
MSOP10	13"	12.4	5.20	3.30	1.20	4.0	8.0	2.0	12.0	Q1
MSOP8	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
TSSOP14	13"	12.4	6.95	5.60	1.20	4.0	8.0	2.0	12.0	Q1
SOP8	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
SOP14	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1
DFN3X3-8	13"	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

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